

IN THE SPECIFICATION:

Please amend the paragraph found on p. 13, lines 9-12 as follows:

FIG. **5B** illustrates a stack **500** of various layers present after the reactive ion etching operation **464** of the method **450** of FIG. **4**. As shown, the reactive ion etching creates a trench **510** through the transfer layer **504** and the ~~etch~~ CMP stop/adhesion layer **506** (if it exists). Such trench **510** terminates at an upper surface of the etch stop layer **502**.